

LPC55S0x/LPC550x

Errata sheet LPC55S0x/LPC550x

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Errata sheet

Document information

Info	Content
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Abstract	LPC55S0x/LPC550x errata



Revision history

Rev	Date	Description
1.5	20221219	Added Section 3.5 “PUF SRAM.1: PUF SRAM needs to be reset during the startup of application to prevent high deep-sleep current consumption.”
1.4	20220513	Added ROM.2: Section 3.4 “ROM.2: ROM API can’t be used correctly to update and read monotonic counter in CFW.VENDOR_USAGE word”.
1.3	20211110	Added CAN-FD.1 note in Section 3.3 “CAN-FD.1: Bus transaction abort could occur when CAN-FD peripheral is using secure alias.”.
1.2	20210810	Added VBAT_DCDC.1: Section 3.2 “VBAT_DCDC.1: The minimum rise time of the power supply must be 2.6 ms or slower for Tamb = -40 C, and 0.5 ms or slower for Tamb = 0 C to +105 C”
1.1	20201006	Second version.
1.0	20200814	Initial version.

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1. Product identification

The LPC55S0x/LPC550x HTQFP64 package has the following top-side marking:

- First line: LPC55S0x/LPC550x
- Second line: JBD64
- Third line: xxxx
- Fourth line: xxxx
- Fifth line: zzyywwxR
 - yyww: Date code with yy = year and ww = week.
 - xR: Device revision A

The LPC55S0x/LPC550x HVQFN48 package has the following top-side marking:

- First line: LPC55S0x/LPC550x
- Second line: JHI48
- Third line: xxxxxxxx
- Fourth line: xxxx
- Fifth line: zzyywwxR
 - yyww: Date code with yy = year and ww = week.
 - xR: Device revision A

2. Errata overview

Table 1. Functional problems table

Functional problems	Short description	Revision identifier	Detailed description
ROM.1	ROM fails to enter ISP mode when image is corrupted with flash pages in an erased or unprogrammed state.	A	Section 3.1
VBAT_DCDC.1	The minimum rise time of the power supply must be 2.6 ms or slower for Tamb = -40 C, and 0.5 ms or slower for Tamb = 0 C to +105 C.	A	Section 3.2
CAN-FD.1	Bus transaction abort could occur when CAN-FD peripheral is using secure alias.	A	Section 3.3.
ROM.2	ROM API can't be used correctly to update and read monotonic counter in CFP.VENDOR_USAGE word	A	Section 3.4
PUF SRAM.1	PUF SRAM needs to be reset during the startup of application to prevent high deep-sleep current consumption.	A	Section 3.5

Table 2. AC/DC deviations table

AC/DC deviations	Short description	Product version(s)	Detailed description
n/a	n/a	n/a	n/a

Table 3. Errata notes

Errata notes	Short description	Revision identifier	Detailed description
n/a	n/a	n/a	n/a

3. Functional problems detail

3.1 ROM.1: ROM fails to enter ISP mode when image is corrupted with flash pages in an erased or unprogrammed state

Introduction

On the LPC55S0x/LPC550x, if the image is corrupted with flash pages in an erased or unprogrammed state, the ROM may fail to automatically enter ISP mode.

Problem

When secure boot is enabled in CMPA, and the flash memory contains an erased or unprogrammed memory page inside the memory region specified by the image size field in the image header, the device does not automatically enter into ISP mode using the fallback mechanism, as in the case of a failed boot for an invalid image. This problem occurs when the application image is only partially written or erased but a valid image header is still present in memory.

Work-around

Perform a mass-erase to remove the incomplete and corrupted image using one of the following methods:

- Execute the erase command using Debug Mailbox. The device will enter directly into ISP mode after exiting the mailbox.
- Enter into ISP mode using the Debug Mailbox command and use the flash-erase command.
- Reset the device and enter into ISP mode using the ISP pin. Use the flash-erase command to erase the corrupted (incomplete) image.

3.2 VBAT_DCDC.1: The minimum rise time of the power supply must be 2.6 ms or slower for Tamb = -40 C, and 0.5 ms or slower for Tamb = 0 C to +105 C

Introduction

The datasheet specifies no power-up requirements for the power supply on the VBAT_DCDC pin.

Problem

The device might not always start-up if the minimum rise time of the power supply ramp is 2.6 ms or faster for Tamb = -40 C, and 0.5 ms or faster for Tamb = 0 C to +105 C.

Work-around

None.

3.3 CAN-FD.1: Bus transaction abort could occur when CAN-FD peripheral is using secure alias.

Introduction

Unlike CM33, for other AHB masters (CAN-FD, USB-FS, DMA), the security level of transaction is fixed based on the level assigned for the master in SEC_AHB->MASTER_SEC_LEVEL register. So, if application needs to restrict the CAN-FD to secure, following steps are required:

- Set the security level of CAN-FD to secure-user (0x2) or secure privilege (0x3) in SEC_AHB->MASTER_SEC_LEVEL register.
- Assign secure-user or secure-privilege level for CAN-FD register space in SEC_AHB-> SEC_CTRL_AHB_PORT8_SLAVE1 Register.
- Assign secure-user or secure-privilege level for message RAM.

Example: If 16KB of SRAM 2 (0x2000_C000) bank is used for CAN message RAM. Then set rules in SEC_AHB-> SEC_CTRL_RAM2_MEM_RULE0 register to secure-user (0x2) or secure privilege (0x3).

Problem

The shared memory used by CAN-FD controller and CPU should be accessible using secure alias with address bit 28 set (example 0x3000_C000). However, when CAN-FD makes a bus transaction using secure alias (address bit 28 set), the transaction is aborted.

Work-around

- When CPU is accessing the CAN-FD register or message RAM it should always use secure alias i.e., 0x3000_C000 for message RAM manipulation. .
- For any structure the CAN-FD peripheral uses to fetch or write, memory should be set to use 0x2000_C000 in order for bus transaction to work. CAN-FD software driver should set “Message RAM base address register (MRBA, offset 0x200)” with physical address of RAM instead of secure alias.

3.4 ROM.2: ROM API can't be used correctly to update and read monotonic counter in CFP.VENDOR_USAGE word

Introduction

Customer Field Programmable Area (CFPA) of Protected Flash Region (PFR) contains VENDOR_USAGE word. The lower 16-bits of the VENDOR_USAGE word implements a monotonic counter which should contain current value or higher value when new version of CFP page is written. Upper 16-bits of the VENDOR_USAGE word should contain inverse value of aforesaid monotonic counter.

Problem

In the ROM, 16-bit monotonic counter is implemented by upper 16-bits of the VENDOR_USAGE word while lower 16-bits contain inverse value of monotonic counter i.e Monotonic Counter and its inverse value are swapped erroneously in the ROM. Due this error, ROM APIs do not access VENDOR_USAGE monotonic counter correctly.

Work-around

User should increment and store Monotonic Counter value in upper 16-bits of VENDOR_USAGE word while inverse value of the monotonic counter should be stored in the lower 16-bits of the VENDOR_USAGE word.

3.5 PUF SRAM.1: PUF SRAM needs to be reset during the startup of application to prevent high deep-sleep current consumption.

Introduction

The LPC55S0x family offers SRAM PUF feature where the PUF provides a unique key per device. By default, the SRAM PUF block is disabled on the LPC550x devices.

Problem

The SRAM PUF block is enabled on the LPC550x devices resulting in higher deep-sleep current. The PUF SRAM block needs to be enabled and reset in order to achieve the deep-sleep current specification.

Work-around

On the LPC550x devices, following software workaround must be applied in the SystemInit function (SDK source file - "system_LPC55xx.c") to prevent high deep-sleep mode current consumption:

- Enable the PUF Clock to access necessary registers.
- Reset the PUF.
- Enabled the PUF SRAM.
- Disable the PUF clock.

```

/* Following code is to reset PUF to remove over consumption */
/* Enable PUF register clock to access register */
SYSCON->AHBCLKCTRLSET[2] = SYSCON_AHBCLKCTRL2_PUF_MASK;
/* Release PUF reset */
SYSCON->PRESETCTRLCLR[2] = SYSCON_PRESETCTRL2_PUF_RST_MASK ;
/* Enable PUF SRAM */
#define PUF_SRAM_CTRL_CFG *((volatile uint32_t*)(0x4003B000u + 0x300u))
#define PUF_SRAM_CTRL_INT_STATUS *((volatile uint32_t*)(0x4003B000u +
0x3E0u))
PUF_SRAM_CTRL_CFG |= 0x01 | 0x04 ;
/* Disable PUF register clock. */
// Delaying the line of code below until the PUF State Machine execution is
completed:
// Shutting down the clock to early will prevent the state machine from reaching the
end.
// => Wait for status bit in PUF Controller Registers before stop PUF clock.
while(!(PUF_SRAM_CTRL_INT_STATUS & 0x1));
SYSCON->AHBCLKCTRLCLR[2] = SYSCON_AHBCLKCTRL2_PUF_MASK;

```

Remark: The SRAM PUF block should not be used on the LPC550x devices and is not guaranteed to function. This feature is only available on the LPC55S0x devices.

4. AC/DC deviations detail

No known errata.

5. Errata notes detail

No known errata.

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